

Emergency Response (D0)

RDA# WW3065621

To: *Insert customer contact here*

Company: DIGI-KEY - Macao Communication **Cust. Ship ID #** 2001366

From: Wai Meng Choy, CSE Manager IRSEA **Location:** IFX Temecula, CA

Date: Feb 10, 2015 **Ph:** +1 (656) 506-2062

CC: *Insert Sales contact,* Joseph DeSalvo, Amado Chaves, Mahmood Choudhry, Stephane Ernoux, Jonathan Emilio, Eddie Yick **Mobile:** +65 (9833) 4887

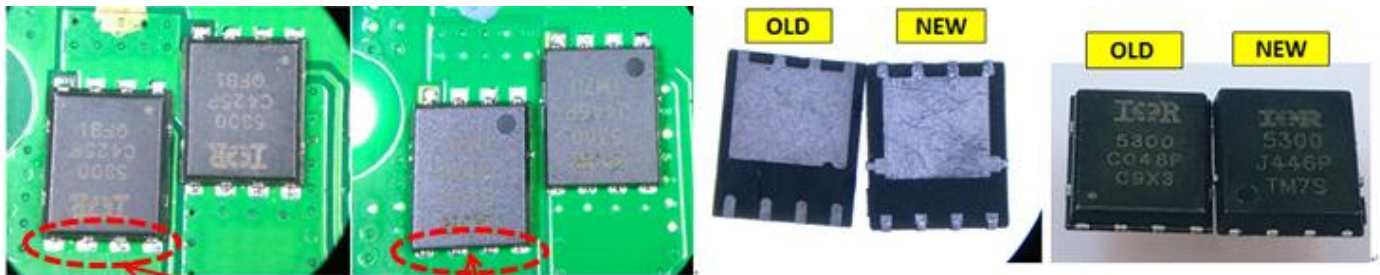
Subject: Potential Unit shifting during board mount process for 5x6 PQFN assembled from ASEWH

Problem Description:

A previous PCN # S20857 & 288-PCN-90 notice did not disclose minor dimensional differences between previous and current assembly houses, although they both meet JEDEC. Units assembled from newly released assembly site ASEWH have been observed to have unit shifting on customer board post reflow. Shifting of device did not cause any functional failures, but physically the unit movement is observable.

Problem verification:

Actual verification of shipped lots showed that unit slightly moved downward compared to units assembled from IR's pilot site.



■ Unit moved but still with solder connection on both ends

Containment Action:

IR has held lots at IR inventory locations for lots produced by new site (ASEWH) and have already alerted all ship to distributors or customers about the POD changes by submitting new PCN with more details regarding the changes.

Delivery	DlvTy	Ship-to	Name of the ship-to party	Material	Deliver	Pick Date	Batch	Purch.Doc
80779984	ZLF	2001366	DIGI-KEY	IRFH8202TRPBF	4,000	11/10/2014	100TA3F.1	469788
80815710	ZLF	2001366	DIGI-KEY	IRLH5036TRPBF	4,000	1/8/2015	100TIN6.1	489443

Please review inventory status and verify product is on hold, then work with your Sales or CSE to review your PCB layout and verify if there is any impact to form or fit.

Root Cause:

Technical Root Cause: POD difference from ASEWH site specifically the E-2 and L dimension had potentially contributed to the unit shift during reflow process. However, take note that based on previous POD analysis/ simulation, the difference was not expected to create any solder ability issue except that there is some visible shifting.

Systemic Root Cause: When process change was reviewed it was judge as a non notifiable change due to meeting JEDEC outline and IR missed difference in POD dimensions and it impact to solder mount operation.

Risk Assessment: Product may shift on board from previous IR product supplied and may cause alarm at visual inspection due to abnormal behavior from normal experience of product location on the board. Please see revised PCN and technical details for customer review.

Corrective Action:

1. Re-issue PCN with detailed POD changes, see attached
2. Address Process Change Review procedure to prevent re-occurrence by ensuring all changes are disclosed to Operations review team to verify what change notification details are required for future PCN's.

If you have any question regarding this response, please do not hesitate to contact us.